

v03.0810



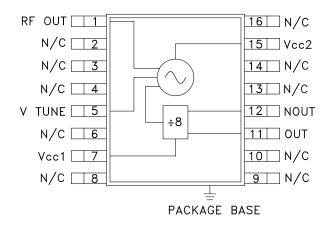
KU-BAND MMIC VCO WITH DIVIDE-BY-8 13.2 - 13.5 GHz

Typical Applications

Low noise MMIC VCO w/Divide-by-8 for Ku-Band applications such as:

- Point-to-Point Radios
- Point-to-Multi-Point Radios / LMDS
- VSAT

Functional Diagram



Features

Pout: -7 dBm

Phase Noise: -105 dBc/Hz @100 KHz Typ.

No External Resonator Needed Single Supply: 5V @ 290 mA QSOP16G SMT Package

General Description

The HMC401QS16G & HMC401QS16GE are GaAs InGaP Heterojunction Bipolar Transistor (HBT) MMIC VCOs. The HMC401QS16G & HMC401QS16GE integrate resonators, negative resistance devices, varactor diodes and divide-by-8 prescalers. The VCO's phase noise performance is excellent over temperature, shock, and process due to the oscillator's monolithic structure. Power output is -7 dBm typical from a 5V supply voltage. The voltage controlled oscillator is packaged in a low cost, surface mount 16 leaded QSOP package with an exposed base for improved RF and thermal performance.

Electrical Specifications, $T_A = +25^{\circ}$ C, Vcc1, Vcc2 = +5V

| Parameter | | Min. | Тур. | Max. | Units |
|--|-----------------------------|-----------|-------------------------|------|--------------------------|
| Frequency Range | | | 13.2 - 13.5 | | GHz |
| Power Output | FR Output Divided Output | -10 -9 | -7 -6 | | dBm dBm |
| SSB Phase Noise @ 100 kHz Offset, Vtune= +5V @ RF Output | | | -105 | | dBc/Hz |
| Tune Voltage | Vtune | 0 | | 10 | V |
| Supply Current | Icc1 (Digital) Icc2 (RF) | | 65 225 | | mA mA |
| Tune Port Leakage Current (Vtune= 10V) | | | | 10 | μA |
| Output Return Loss | | | 2 | | dB |
| Harmonics/Subharmonics | 1/2 3/2 2nd 5/2 | | -7 -28 -17 -40 | | dBc dBc dBc dBc |
| Pulling (into a 2.0:1 VSWR) | | | 0.6 | | MHz pp |
| Pushing @ Vtune= 5V | | | 5 | | MHz/V |
| Frequency Drift Rate | | | 1.5 | | MHz/°C |

HMC401* PRODUCT PAGE QUICK LINKS

Last Content Update: 02/23/2017

COMPARABLE PARTS 🖵

View a parametric search of comparable parts.

EVALUATION KITS

· HMC401QS16G Evaluation Board

DOCUMENTATION

Data Sheet

• HMC401 Data Sheet

REFERENCE MATERIALS -

Quality Documentation

- HMC Legacy PCN: QS##, QS##E and QS##G,QS##GE packages - Relocation of pre-existing production equipment to new building
- Package/Assembly Qualification Test Report: Plastic Encapsulated QSOP (QTR: 02015 REV: 11)
- Semiconductor Qualification Test Report: GaAs HBT-A (QTR: 2013-00228)

Technical Articles

Low Cost Plastic MMIC VCOs

DESIGN RESOURCES 🖵

- HMC401 Material Declaration
- PCN-PDN Information
- · Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

View all HMC401 EngineerZone Discussions.

SAMPLE AND BUY 🖵

Visit the product page to see pricing options.

TECHNICAL SUPPORT

Submit a technical question or find your regional support number.

DOCUMENT FEEDBACK 🖳

Submit feedback for this data sheet.

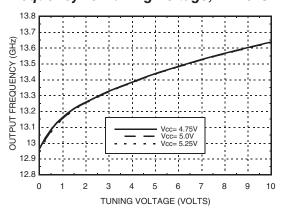


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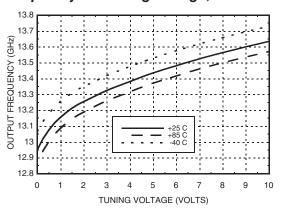


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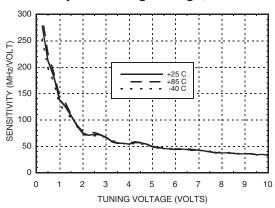
Frequency vs. Tuning Voltage, T= 25°C



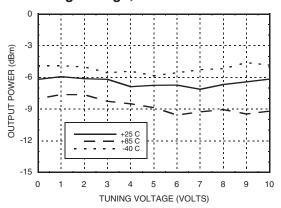
Frequency vs. Tuning Voltage, Vcc= +5V



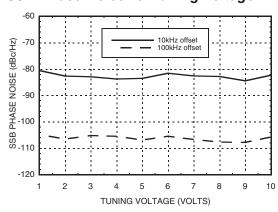
Sensitivity vs. Tuning Voltage, Vcc= +5V



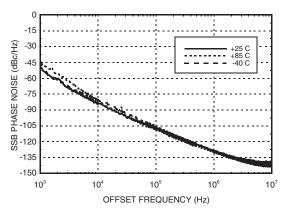
Output Power vs. Tuning Voltage, Vcc= +5V



SSB Phase Noise vs. Tuning Voltage



Phase Noise @ Vtune= 5V



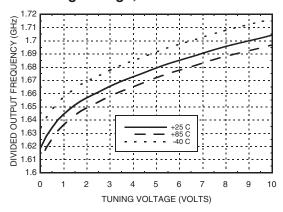


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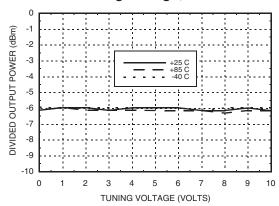


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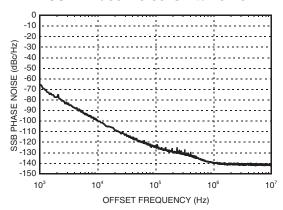
Divided Frequency vs. Tuning Voltage, Vcc= +5V



Divided Output Power vs. Tuning Voltage, Vcc= +5V



Divided Output SSB Phase Noise @ Vtune= 5V



Absolute Maximum Ratings

| Vcc1, Vcc2 | 5.5 V |
|-----------------------|----------------|
| Storage Temperature | -65 to +150 °C |
| Operating Temperature | -40 to +85 °C |
| Vtune | 0 to 11V Max. |
| ESD Sensitivity (HBM) | Class 1A |

ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS

Typical Supply Current vs. Vcc

| Vcc (V) | Icc (mA) |
|---------|----------|
| 4.75 | 260 |
| 5.0 | 290 |
| 5.25 | 315 |

Note: VCO will operate over full voltage range shown above.

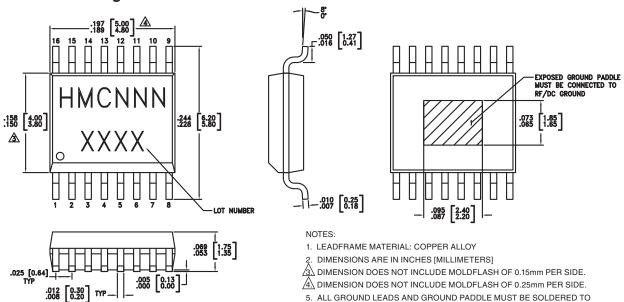


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KU-BAND MMIC VCO WITH DIVIDE-BY-8 13.2 - 13.5 GHz

Outline Drawing



Package Information

| Part Number | Package Body Material | Lead Finish | MSL Rating | Package Marking [3] |
|--------------|--|---------------|------------|---------------------|
| HMC401QS16G | Low Stress Injection Molded Plastic | Sn/Pb Solder | MSL1 [1] | HMC401 XXXX |
| HMC401QS16GE | RoHS-compliant Low Stress Injection Molded Plastic | 100% matte Sn | MSL1 [2] | HMC401 XXXX |

PCB RF GROUND.

- [1] Max peak reflow temperature of 235 $^{\circ}\text{C}$
- [2] Max peak reflow temperature of 260 $^{\circ}\text{C}$
- [3] 4-Digit lot number XXXX

Pin Descriptions

| Pin Number | Function | Description | Interface Schematic | |
|-------------------------------------|----------|---|----------------------|--|
| 1 | RFOUT | RF output (AC coupled). | RFOUT | |
| 2, 3, 4, 6, 8, 9, 10, 13, 14, 16 | N/C | No Connection | | |
| 5 | VTUNE | Control Voltage Input. Modulation port bandwidth dependent on drive source impedance. | 7.5nH 1500 VTUNEO | |



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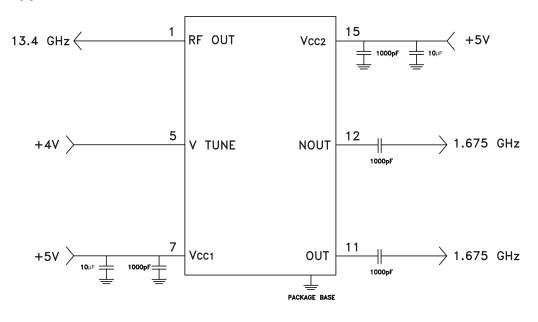


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Pin Descriptions

| Pin Number | Function | Description | Interface Schematic |
|------------|------------|---|---------------------|
| 7, 15 | VCC1, VCC2 | Supply Voltage, 5V | Vcc O26pF |
| 11 | OUT | Divided Output | 5V OUT |
| 12 | NOUT | Divided Output 180° output phase with pin 11. | 5V ONOUT |
| | GND | Package bottom has an exposed metal paddle that must be RF & DC grounded. | GND = |

Typical Application Circuit



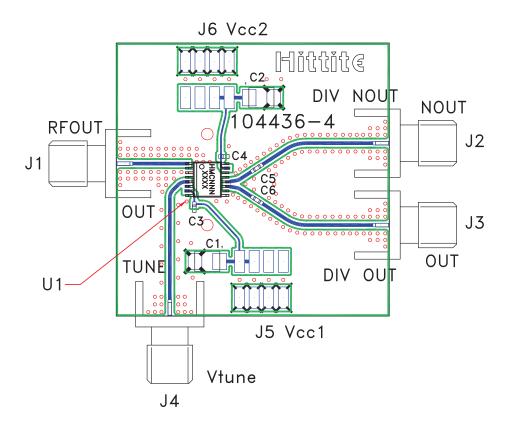


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Evaluation PCB



List of Materials for Evaluation PCB 104711 [1]

| Item | Description |
|---------|--------------------------------|
| J1 - J4 | PCB Mount SMA RF Connector |
| J5 - J6 | 2 mm DC Header |
| C1 - C2 | 10 μF Tantalum Capacitor |
| C3 - C6 | 1,000 pF Capacitor, 0402 Pkg. |
| U1 | HMC401QS16G / HMC401QS16GE VCO |
| PCB [2] | 104436 Eval Board |

[1] Reference this number when ordering complete evaluation PCB $\,$

[2] Circuit Board Material: Rogers 4350

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and backside ground slug should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.